Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	3	"4242157".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:00
L3	30	("2708650" | "2731378" | "2925193" | "3581375" | "3604108" | "3615946" | "3658618" | "3693252" | "3992236" | "4102039").PN. OR ("4242157"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 10:15
L4	7666	(organic near3 ceramic) or (organic$ceramic)\	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 10:16
L5	7666	(organic near3 ceramic) or (organic$ceramic)	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 10:16
L6	1504	5 and (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:17
L7	249	5 with(pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:17
L16	313	rigid$flex (".rigid" near2 flex)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:38
L17	1724	rigid$flex ("rigid" near2 flex)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:38
L18	31	17 with (organic ceramic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:39

L19	6137	361/792.ccls. 174/255,252.ccls. 428/209.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:40
L20	499	19 and @pd>"20041005"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:41
L21	113	19 and @pd>"20051005"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 12:29
L22	22017	organic and ceramic and substrate	US-PGPUB	OR	ON	2006/02/02 12:30
L23	2	organic with ceramic with substrate with component with conductor	US-PGPUB	OR	ON	2006/02/02 12:30
S1	1025	361/792.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:32
S2	105	S1 and (organic and ceramic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:32
S3	3850	361/762,761,764,795,792.ccls. or 174/256,258.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:55
S4	553	S3 and organic and ceramic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:55
S5	55	S3 and (heatsink or heat$sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:57

S6	6	S4 and (heatsink or heat$sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:01
S7	4	"6180436".pn. "6365964".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:01
S8	1161	(ceramic near substrate) and (organic near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:14
S9	603	S8 and (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:17
S10	0	174/255-259,252	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:00
S11	4356	174/255-259,252.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:01
S12	2322	S11 and (cermanic or non$organic "metal oxide" "metal nitride" oxide nitride organic plastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:26
S13	1730	S12 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:12

S14	1411	S13 and (conductor or wire or trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:12
S15	1231	S14 and @pd<"20040401"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:27
S16	824	S11 and (cermanic or non$organic "metal oxide" "metal nitride" oxide nitride) and (organic plastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:27
S17	720	S16 and @pd<"20040401"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:27
S18	581	S17 and (conductor wire trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:36
S19	0	(ceramic and organi).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:36
S20	2866	(ceramic and organic).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:36
S21	434	S20 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:42

S22	28	S21 and (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:37
S23	5481	(organic with ceramic with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:42
S24	574	S23 same (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:33
S25	5788	428/209,210,901.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 14:25
S26	455	S25 and (ceramic with organic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 14:28
S27	763999	chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:14
S28	27	("5036431" | "5311402" | "5481435" | "5614766").PN. OR ("5936843").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/05 08:23
S29	20	("5072075" | "5483421" | "5491303" | "5574630" | "5615087" | "5689091" | "5808873" | "5815374" | "5894173" | "5900675" | "5936843" | "5962922" | "6137062" | "6162997" | "6163462" | "6239980" | "6271478" | "6288347" | "6335495").PN. OR ("6538213").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/05 08:28

S30	5481	(organic with ceramic with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:34
S31	574	S30 same (pcb or "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:34
S32	450	S31 and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:43
S33	116	S31 same component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:38
S34	1223090	S32 amd (traces or conductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:43
S35	321	S32 and (traces or conductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:57
S36	5788	428/209,210,901.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:57
S37	175	S36 and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 08:57

S38	23	("4680220" | "4810563" | "4849284" | "4882455" | "5061548" | "5139852" | "5213878" | "5277725" | "5287619" | "5358775" | "5384181" | "5541249" | "5552210" | "5571609" | "5670262" | "5733640" | "5919546" | "5922453" | "5965273").PN. OR ("6528145").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/05 08:58
S39	4	"power integrated circuit chip" with "ceramic substrate"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 09:35
S40	0	10/708935	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 09:47
S41	0	"10708935"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 09:47
S42	0	"10/708935"	US-PGPUB	OR	ON	2005/10/05 09:48
S43	15	oman.inv.	US-PGPUB	OR	ON	2005/10/05 09:49
S44	8	degenkolb.inv.	US-PGPUB	OR	ON	2005/10/05 09:49
S45	9298479	(ceramic near substrate) with (organic near substrate) wit (adjacent or beside or parallel or connected)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 10:27
S46	6	(ceramic near substrate) with (organic near substrate) with (adjacent or beside or parallel or connected)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 10:27
S47	535	hybrid with (pcb "circuit board") with ceramic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:00

S48	25	hybrid with (pcb "circuit board") with ceramic with organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 15:39